

# A TPC with Micromegas-based Readout as the Central Tracker for Future Colliders



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# International Large Detector (ILD)

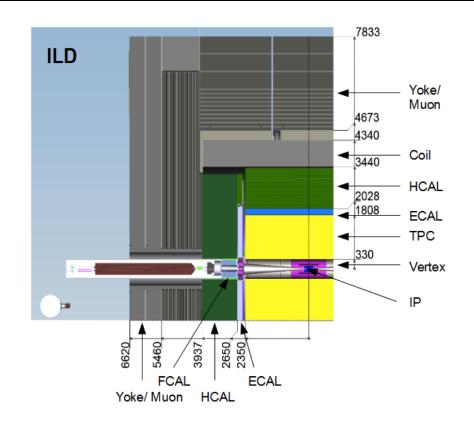


# International Linear Collider (ILC) project in Japan:

- energy range (baseline design): staged project starting at 250 GeV
- **ILC** is planned with two experiments
- TPC is the central tracker for International Large Detector (ILD)

#### **ILD components:**

- vertex detector
- few layers of silicon tracker
- gaseous TPC
- **ECAL/HCAL/FCAL**
- superconducting coil (3.5 T)
- muon chambers in iron yoke



#### **ILD requirements:**

momentum resolution:

$$\delta(1/p_{\mathrm{T}}) \leq 2 \times 10^{-5} \mathrm{GeV^{-1}}$$

- impact parameters:  $\sigma(r\phi) \leq 5\mu m$
- jet energy resolution:

$$\sigma_{\rm E}/{\rm E} \sim 3-4\%$$



# Detector Optimization

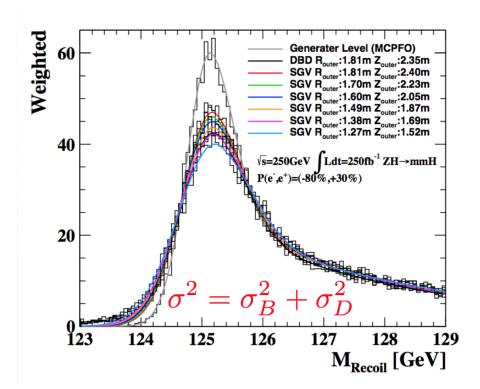


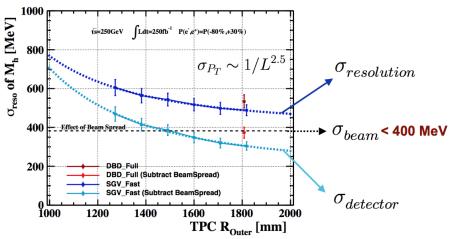
$$rac{\sigma(\mathsf{p_T})}{\mathsf{p_T}} = \sqrt{rac{720}{\mathsf{N+4}}} (rac{\sigma_\mathsf{x} \mathsf{p_T}}{0.3 \mathsf{BL}^2})$$

- TPC point resolution is x10 worse than Si
  - would need x100 more points
  - not always practical
  - larger tracking volume
  - include 2 inner Si layers (SIT) and 1 outer Si layer (SET)

#### ILC flagship measurement

- $^{"}$  recoil mass  $e^+e^- o Z(ll)X$
- driven by both beam spread  $(\sigma_{
  m B})$  and momentum resolution $(\sigma_{
  m D})$ 
  - $\rightarrow \sigma_{\rm B} = 400~{
    m MeV}$  from TDR
  - $ightarrow \sigma_{
    m D} = 300~{
    m MeV}$  at  ${
    m R}_{
    m out} = 1.8~{
    m m}$
  - $ightarrow \sigma_D = 400 \; MeV \; \text{at R}_{\text{out}} = 1.4 \; \text{m}$







### Time Projection Chamber for ILD



# TPC is the central tracker for International Large Detector (ILD)

- $\square$  Large number of 3D points ( $\sim$  200)
  - continuous tracking
- Particle identification
  - $\rightarrow$  dE/dx measurement
- Low material budget in front of the calorimeters (Particle Flow Algorithm)
  - $\rightarrow$  barrel:  $\sim 5\% X_0$
  - $^{ imes}$  endplates:  $\sim 25\% {
    m X}_0$
- Two gas amplification options:
  - **Gas Electron Multiplier (GEM)**
  - **™** MicroMegas (MM)
    - → pad-based charge dispersion readout
    - → direct readout by the TimePix chip



### TPC Requirements in 3.5 T

- **™** Momentum resolution:
  - →  $\delta(1/p_T) \le 9 \times 10^{-5} \text{GeV}^{-1}$
- **Single hit resolution:** 
  - $\rightarrow \sigma(r\phi) \le 100 \mu m$  (overall)
  - $\rightarrow \sigma(Z) \simeq 400 \mu m$  at z=0
- **Tracking efficiency:** 
  - $\rightarrow$  97% for  $p_T \ge 1 GeV$
- **dE/dx resolution:** 5%

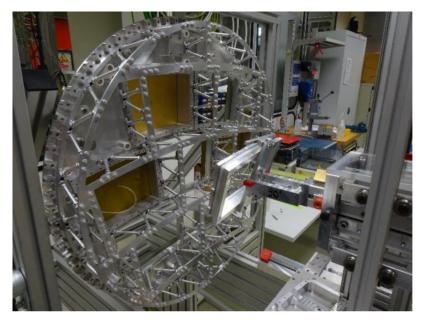


# Large Prototype and TPC Mechanics



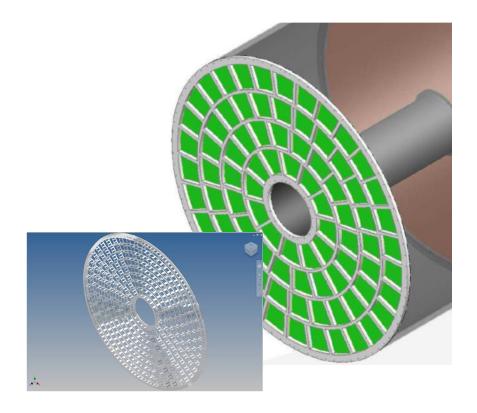
#### **☞** Gravitational loads:

- self-weight of structure: 895 kg
- weight of modules: 1176 kg
  - → 84 modules
  - → 7 kg/super-module (4-ring)
  - → endplate
- total weight 2000 kg



LP endplate with 7 windows to receive up to 7 fully equipped identical modules

8-ring: 4 modules combined in 1 super-module



ILD TPC is 3.5x size/B field of the Large Prototype (LP) operating in B=1 T

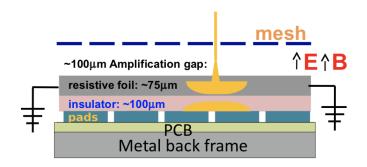


### Resistive Micromegas Prototype



#### Pad size limits transverse resolution

use resistive anode to spread charge



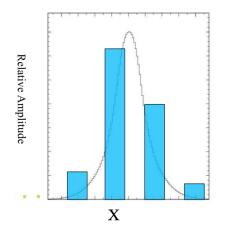
Charge density function of time dependent charge dispersion on 2D continuous RC network:

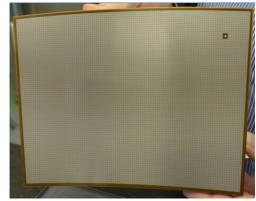
$$ho(\mathrm{r,t}) = rac{\mathrm{RC}}{2\mathrm{t}} \exp[-rac{-\mathrm{r^2RC}}{4\mathrm{t}}]$$

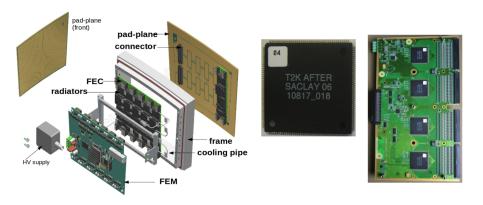
R- surface resistivity

C- capacitance/unit area

Relative fraction of charge seen by pads fitted by Pad Response Function (PRF)







Module readout with 6 FE cards bearing 4 AFTER ASICs chips (12-bit ADC)



### Trigger and DAQ



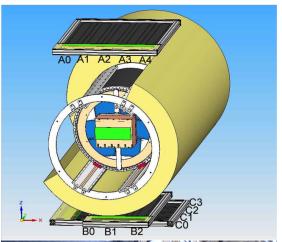
# The test beam facility at DESY provides a 6 GeV electron beam

#### Beam, Laser, and Cosmic triggers are deployed

- A cosmic trigger based on
  - → 12 scintillator plates
  - → readout by silicon PMs
  - → SiPM signal discrimination and coincidence logic with NIM modules

#### Readout system and DAQ

- 120 Hz maximum event taking rate
  - → 6 ASICs chips are digitized in parallel by 12-channel ADC
  - → 4 sequential iterations are needed to readout a whole module
  - → irreducible dead-time of 8 ms



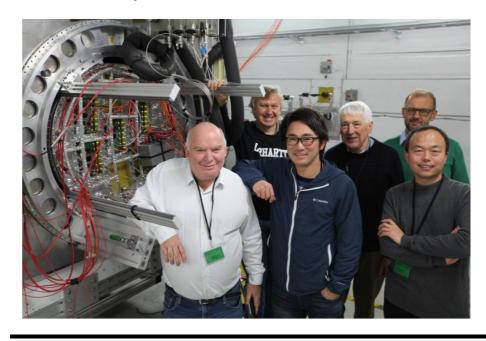


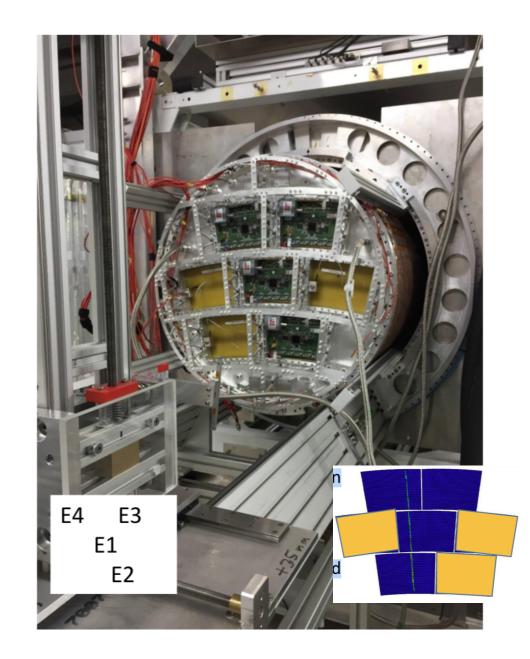






- 4 new Micromegas modules tested in November 2018 at DESY facility (NIM paper)
  - new endplate LP2
  - **1-loop 2-Phase** CO<sub>2</sub> cooling
  - improved mechanics: 99.9% good connections
  - new grounding scheme: encapsulated resistive anode





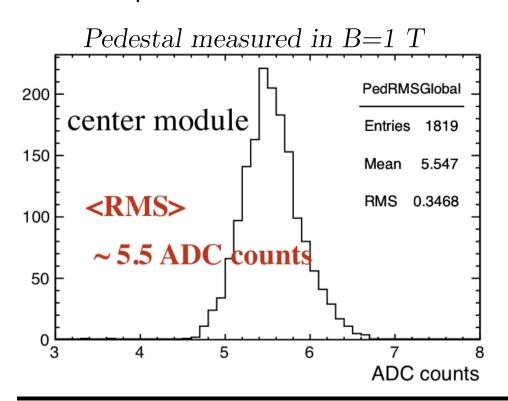


### Modules' Quality

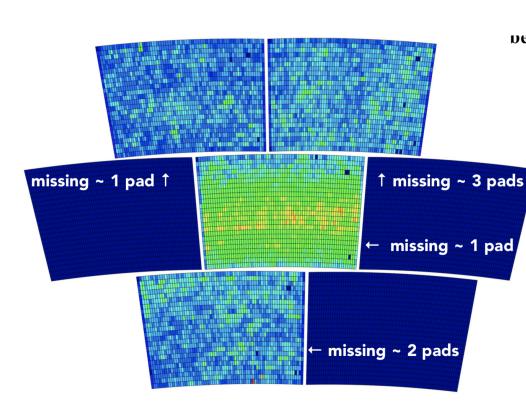


### Measure the quality of connection from pedestal rms and occupancy

- Due to error in electric circuit **2** pads in each module are missing
  - can be fixed in next production
- 1-4 missing pads in each module due to bad pins in connector



# Measured occupancy from accumulated cosmic ray events



Very good electrical connection between pads (PCB) and FEC (99.9%)

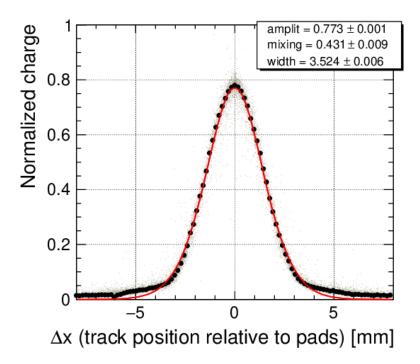


# Uniformity of the Charge Spread

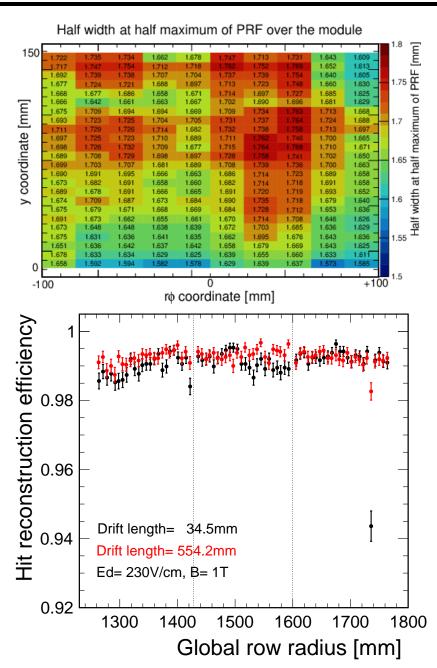


# Calibration of the Pad Responce Function (PRF) is done for each z position

- $\sigma \sim 1.4 \mathrm{mm}$  is expected for
  - $\rightarrow$  R=2.5 M $\Omega$ / $\Box$
  - → 200 ns shaping time
  - $\rightarrow$  200+50 $\mu m$  kapton



50 mm drift distance





#### Residual Estimator and Corrections



#### The resolution is determined from the same statistical sample utilized for the track fit

The geometric mean of inclusive and exclusive residuals in the entire 3D track fit provides unbiased resolution estimator [R.Carnegie, et.al., NIM **A538** 372 (2005)]

$$oldsymbol{\sigma_{
m i}} = \sqrt{\sigma_{
m in} \cdot \sigma_{
m ex}^{
m i}}$$

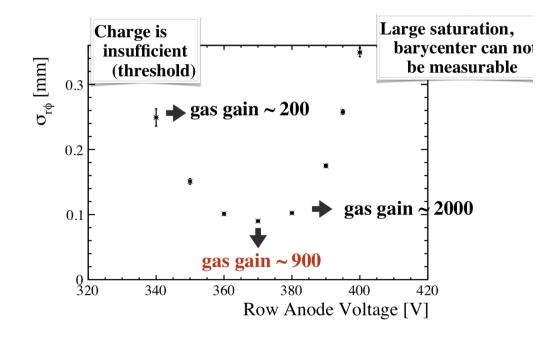
$$\sigma = \mathbf{x}_{\text{track}} - \mathbf{x}_{\text{hit}}$$

#### $\square$ Important requirements for $\sigma_i$ :

- **gaussian-like** 
  - → low fraction of outliers
- **≡** zero off-set
  - → systematic error

# $\sigma_{{ m r}\phi}$ as a function of anode voltage (amplification):

find  $V_{\rm mesh} = 370 V$  to be optimal



#### **™** Corrections to be applied

- **bias:** determined by local RC properties
- distortions: driven by ExB effects
- **alignment:** measure with B=0 T data



# Transverse and Longitudinal Resolutions (B=1T)



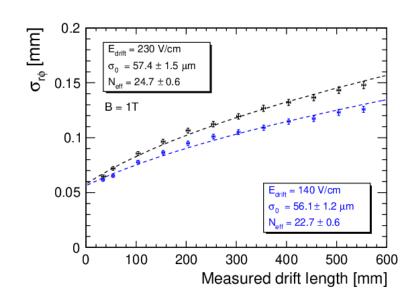
# The readout modules of the prototype operate in a 1 T magnetic field

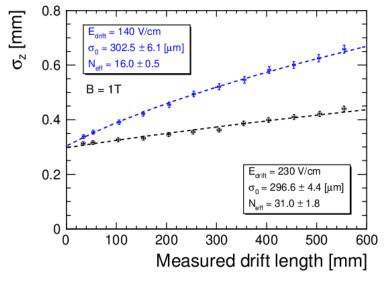
- The performance is estimated solely using the central module
  - a few pad rows on lower and upper modules exhibit degradation due to misalignment of electrods inside the field cage and the inhomogeneity of the resistive anode

#### Fit data with:

$$oldsymbol{\sigma_{ ext{r}\phi/ ext{z}}^2( ext{z}) = \sigma_{ ext{r}\phi0/ ext{z}0}^2 + rac{ ext{D}_{oldsymbol{\perp}/\parallel}^2}{ ext{N}_{ ext{eff}}} ext{z}}$$

- $\sigma_0$  the resolution at z=0,  $N_{\rm eff}$  the effective number of electrons
- Magboltz calculations yield  $D_{\perp/\parallel}$  with approximately 3% precision





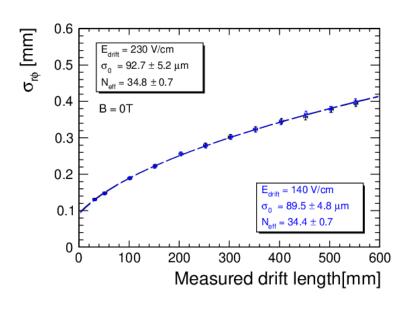


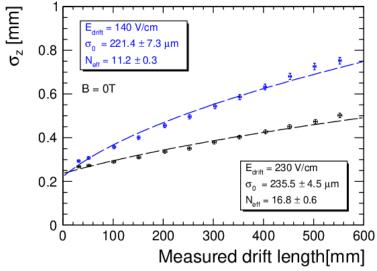
# Transverse and Longitudinal Resolutions (B=0T)



# Data recorded at a 0 T magnetic field are essential for computing the alignment parameters of the modules

- A straight line is used as the track model
- Alignment primarily relies on data satisfying stringent track quality criteria at B=0 T
  - iteratively minimize the  $\chi^2$  addressing rotations and translations of the modules, with the central module serving as a reference
  - iterative procedure continues until the parameters fall withing their uncertainties
  - achieve convergence of all alignment parameters after four iterations





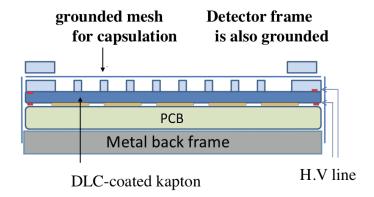


#### Track Distortions

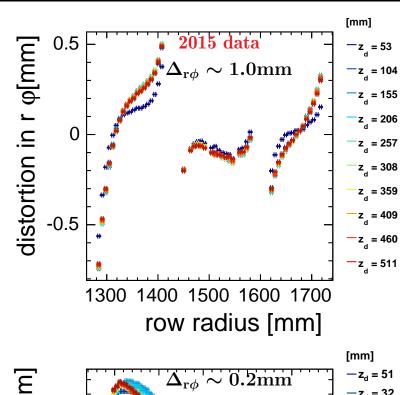


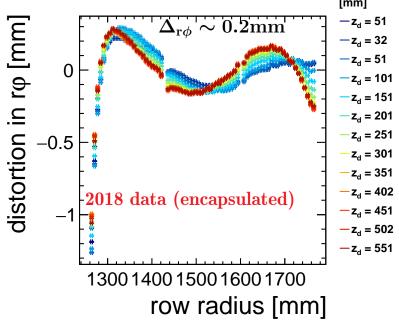
# Non-uniform E-field near module boundaries induces ExB effects

- Track distortions in standard scheme
  - reach about 0.5 mm at boundaries
  - worth to minimize at design level
  - □ accounted as systematic error
- Encapsulated scheme (2018) to reduce distortions at the edges of modules
  - mesh at ground (same as the frame)
  - resistive anode at the +ve HV



ExB effect between modules is effectively suppressed in the new scheme

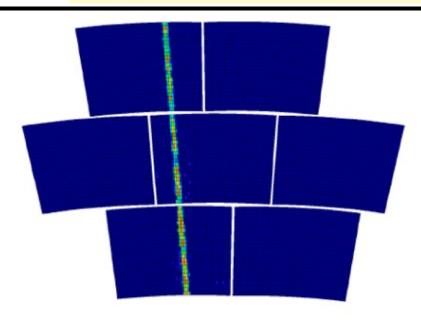






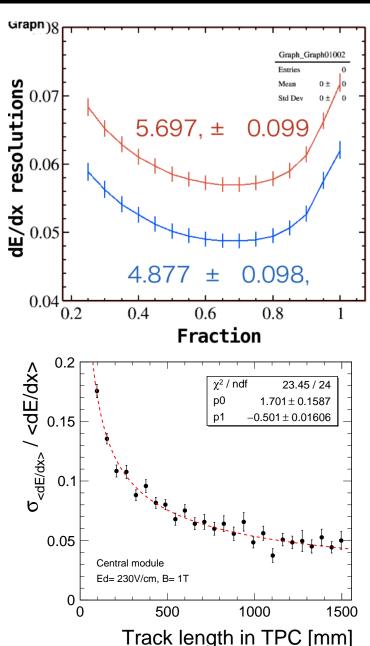
### dE/dx Resolution





# Measuring dE/dx resolution with LP and extrapolating to ILD TPC

- Test arbitrary track lengths by randomly combining hits from several real tracks to create a pseudo track in the TB setup
- Estimated dE/dx resolution using a 70% truncated mean for the ILD TPC
  - $\sigma_{\rm dE/dx} = 4.9\%$  for 192 hits (large ILD)
  - $\sigma_{\rm dE/dx} = 5.7\%$  for 144 hits (small ILD)





# Track Angle Effect

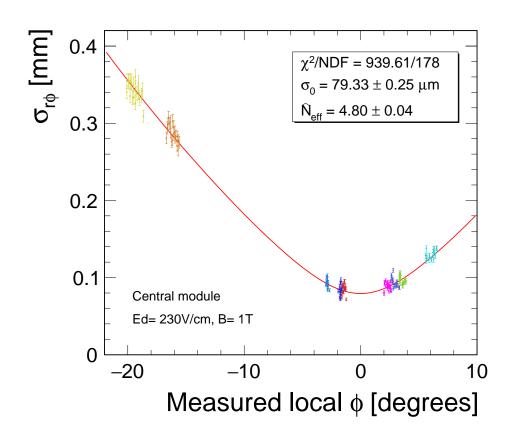


The primary goal is to achieve the utmost point resolution for radial high-momentum tracks emenating from the Interaction Point (IP)

- Resolution degrades with deviation from 0 of the local angle between pad axis and track  $(\phi)$ , due to fluctuations in cluster size during ionization
- Conducted the experiment with the TPC azimuthally rotated  $[-20^{\circ}, +10^{\circ}]$

$$\sigma_{r\phi}^2 = \sigma_{r\phi0}^2 + rac{h^2 an^2\phi}{12} \cdot rac{\cos\phi}{\hat{N}_{ ext{eff}}}$$

 $\hat{N}_{\rm eff} \simeq 5.1$  is expected for h=7 mm [M. Kobayashi, et al., NIM A (764), 394]



Each data point corresponds to a distinct pad row, with a fixed drift distance of 50 mm

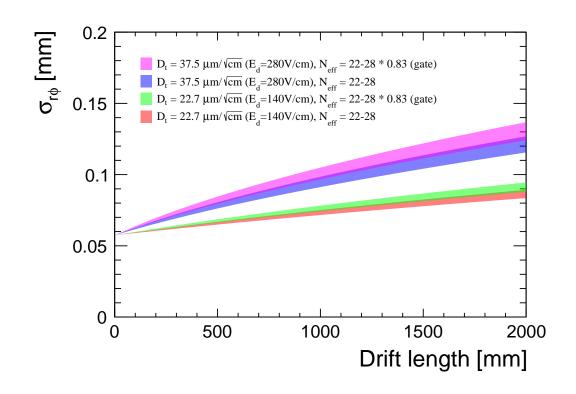


# Extrapolation to ILC Operational Conditions



Extrapolation of resolution for a magnetic field of 3.5 T and 2.35 m drift length (ILD design) relies on a simple empirical function

- Transverse diffusion  $D_{\perp}$  is determined using a Magboltz simulation
- Values for  $\sigma_{r\phi0}$  and  $N_{\mathrm{eff}}$  are derived from the fit to the measured resolution
- Impact of the dynamic gate using a large apperture GEM is demonstrated with an electron transmission of 83% [M. Kobayashi, et al., NIM A (918), 41-53]
  - insights into the perspectives for TPC at circular colliders will be presented in P. Colas talk



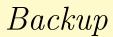
Resolution of about  $100\mu m$  across the entier drift length in the ILD TPC is feasible when stringent control is maintained over gas quality, and impurities are minimized.



#### Conclusions



- Extensive R&D work has been undertaken for the Micromegasbased readout prototype modules, marking a crucial phase in engineering toward the final design of a TPC for ILD
- Comprehensive test of the Encapsulated Resistive-Anode with the grounded mesh scheme of the Micromegas detector performed with a 5 GeV electron beam, demonstrates excellent performance
  - $\sigma_{r\phi}$  at  $z = 0 \simeq 60 \mu m$  and  $\sigma_{r\phi} \leq 100 \mu m$  $\sigma_z$  at  $z = 0 \simeq 200 \mu m$  and  $\sigma_z \leq 400 \mu m$
  - field distortions near the edges, resulting from the ExB effect showed a notable reduction compared to the standard scheme.
- The Encapsulated Resistive-Anode Micromegas detector meets the performance requirements for the central tracker of ILD
  - NIM paper summarizing comprehensive results from the beam test for the Micromegas prototypes is imminient







Backup

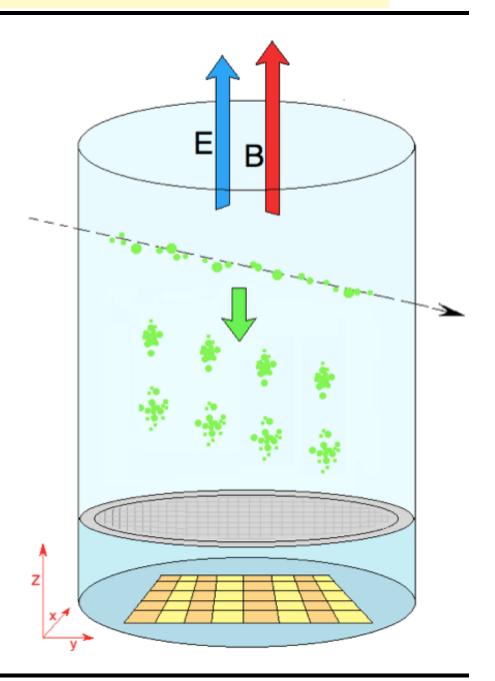


# TPC Principle



A Time Projection Chamber (TPC) is a detector consisting of a cylindrical gas chamber and a position sensitive readout endcaps

- The TPC acts as a 3D camera taking a snapshot of the passing particle
- Transverse and Longitudinal resolutions are major characteristics of the TPC
  - **XY position:** charged particles ionize the gas, a longitudinal electric field causes ionization e<sup>-</sup> to drift towards endcap where they are detected (transverse resolution)
  - **Z position:** measure time between ionization and detection multiply by drift velocity (longitudinal resolution)





# Micro Pattern Gas Detectors (MPGDs)



#### Technology choise for TPC readout: Micro Pattern Gas Detector (MPGD)

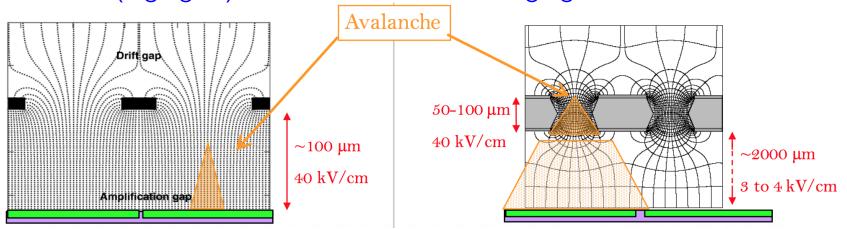
- no ExB effect, better ageing, low ionback drift
- easy to manufacture, MPGD more robust mechanically than wires

#### Resistive Micromegas (MM)

- **™** MICROMEsh GAseous Structure
- metalic micromesh (pitch  ${\sim}50~\mu\mathrm{m}$ )
- $\blacksquare$  supported by 50  $\mu \mathrm{m}$  pillars
- multiplication between anode and mesh (high gain)

#### **GEM**

- **Gas Electron Multiplier**
- doublesided copper clad Kapton
- multiplication takes place in holes,
- 2-3 layers are needed to obtain high gain



Discharge probability can be mastered (use of resistive coatings, several step amplification, segmentation)



# TPC Field Cage



#### ™ Overpressure 3 mbar

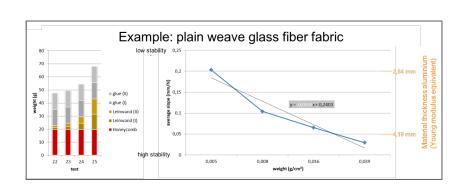
- pressure applied on the cage
- forces applied on each endplate with the pressure on modules

#### Requires a mandrel

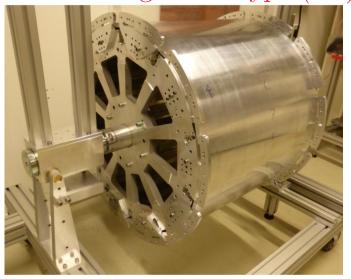
- to shape the composite material (Kapton with copper strips)
- to install flanges

#### Field cage V2 of LP under development

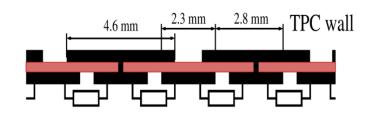
- studies different wall structures ongoing
  - → glass fibers, glue, honeycomb



#### V2 TPC Large Prototype (LP)









# TPC Mechanical Precision/Alignment



#### Required resolution

- electric field homogeneity:  $\Delta E/E \leq 10^{-4}$
- mapping of B field to  $10^{-4}$
- high precision/stability of TPC field cage

#### $\square$ Large prototype (B=1 T):

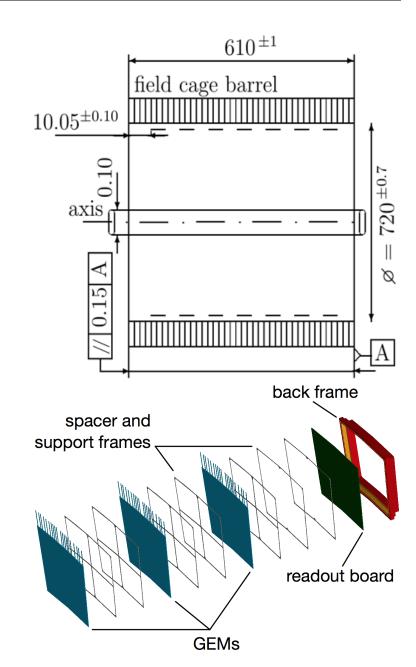
- $\implies$  axis alignment  $\leq 0.1 \mathrm{mm}$
- $\rightarrow$  cathode/anode  $\parallel \leq 0.15 \mathrm{mm}$
- max. bending  $\perp$  to Z (middle):  $\sim 0.02 \mathrm{mm}$
- less critical: length to 1mm and  $\varnothing$  to 0.7 mm

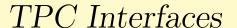
#### ILD TPC (3.5x size/B field):

- $\implies$  axis alignment  $\leq 0.3 \text{mm}$
- $\rightarrow$  cathode/anode  $\parallel \leq 0.45 \mathrm{mm}$

#### Precise alignment of readout structures

- all parts produced to a precision  $\mathcal{O}(0.05 \text{ mm})$
- stable aluminum backframe
- well established with Millepede II (test beam)











# Wery High Voltage for the central cathode:

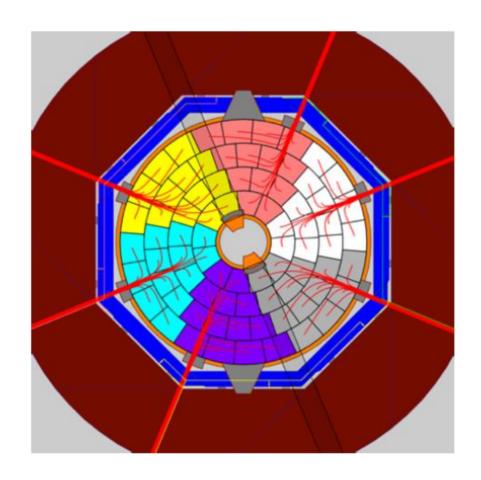
- very big cable (insulation)
- curvature radii 70mm to 280mm

#### **™** Low-voltage power:

- bundles of 10 copper cables
- $\rightarrow$  6mm<sup>2</sup> section (32 A)
- **■** 6 sectors per end-plate:
- 120 cables, 12kW(100 W per cable)
- 20 m cables (R=0.06  $\Omega$ )  $\rightarrow$ 60 W loss (60% of the useful power)
  - → cable cooling? DC-DC converters?

Detector HV and fibres for readout are less demanding

# Patch panels on each sector to allow disconnecting the TPC



Possibly need a jacket against heat from the ECAL



# Prototype Technologies (GEM)



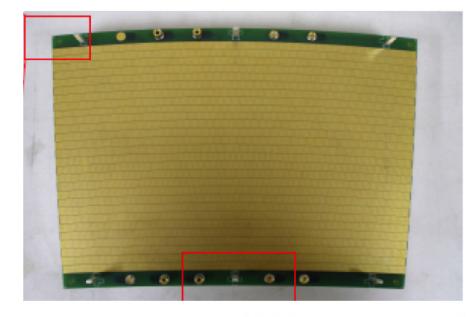
#### **Triple GEM Modules**

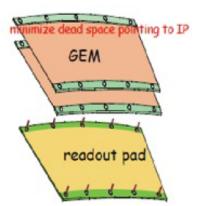
# drift volume $2 \, \text{mm}$ $E_{Transfer} = 1500 \text{ V/cm}$ 250 V mm $E_{Transfer} = 1500 \text{ V/cm}$ 250 V шш E<sub>Induction</sub>= 3000 V/cm pad plane back frame spacer and support frames readout board **GEMs**

#### GEM: modified ALTRO readout

■ 16-channel ALTRO chip (10-bit)

#### **Double GEM Modules**





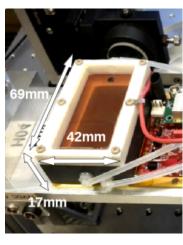




### Highly Pixelated Readout (TimePix)



Single chip (2017)



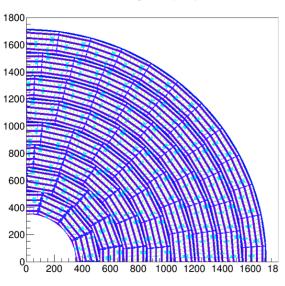
**QUAD** (2018)



Module (2019)



**TPC Plane** 

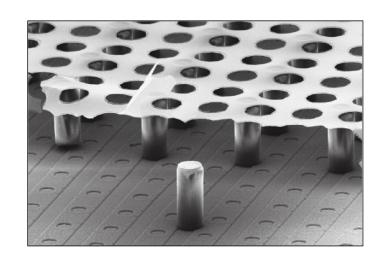


### Micromegas on a pixelchip

- insulating pillars between grid & pixelchip
- one hole above each pixel
- amplification directly above the pixelchip
- very high single point resolution

#### № New QUAD design: Four-TimePix3

- tested in a beam in Bonn (2.5 GeV e<sup>-</sup>)
- improved chip protection against sparks



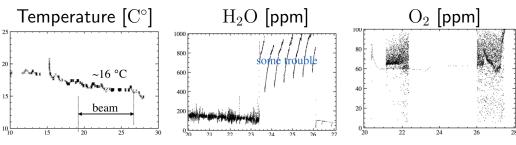


### Calibration and Drift Velocity



#### Prototype operates with T2K gas

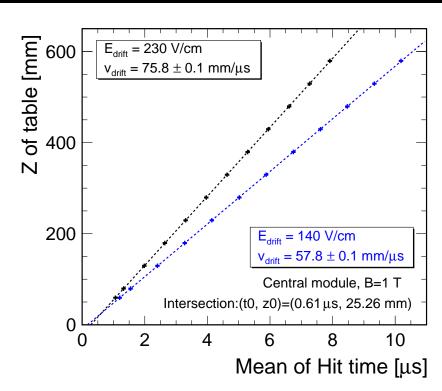
- $\rightarrow$  Ar(95%), CF<sub>4</sub>(3%), iC<sub>4</sub>H<sub>10</sub>(2%)
- gas purity: 100 ppm  $H_2O$ , 60 ppm  $O_2$
- deploy Magboltz calculations

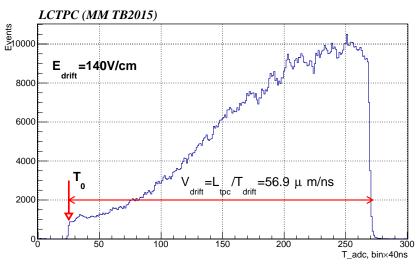


 $\blacksquare$  Absolute  $\mathbf{T}_0$  calibration:

- beam trigger: dedicated z-scan at  $V_{drift} = 140,230 \text{ V}$
- cosmic trigger: accumulate a whole LP volume data events

	E=140 V/cm	E=230 V/cm
$ m V_d$ Data	$56.7 \pm 0.1 \mu \text{m/ns}$	$74.1 \pm 0.2 \; \mu \text{m/ns}$
$ m V_d$ Magboltz	$57.9 \pm 1.0 \mu \text{m/ns}$	$75.5 \pm 1.0 \mu \text{m/ns}$
$\mathrm{D}_{\perp}$ Magboltz	$74.5 \pm 2.5 \mu \text{m}/\sqrt{\text{cm}}$	$94.8 \pm 3.1 \mu \text{m} / \sqrt{\text{cm}}$





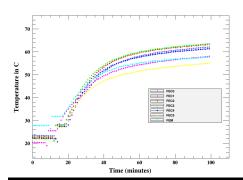


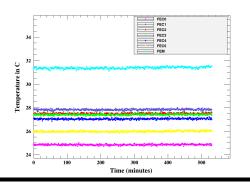
### 2-Phase CO<sub>2</sub> Cooling



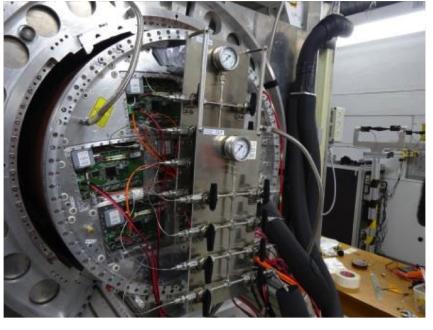
# Cooling of the electronic circuit is required due to power consumption

- Temperature of the circuit rises up to 60°C
  - causes a potential damage of electronics
  - convects gas in TPC due to pad heating
- ing plant TRACI was provided to 7 MM modules during 2014/15 beam tests at DESY
- 2018 tested with 4 modules in one loop
  - $10^{\circ}$ C at P=50 bar system operation
  - about 30°C on the FECs was achieved during 11 days of continuous operation





2-phase  $CO_2$  cooling support



- Thermal behavior and effect of cooling have been simulated
  - D.S. Bhattacharya et al., JINST 10 P08001, 2015



### 3D Cooling Circuit

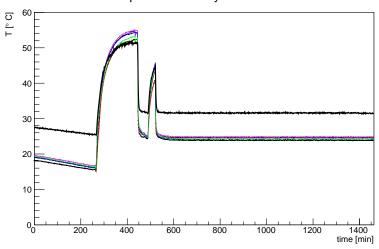


#### **ILD TPC Requirements**

- about 1kW heat transfer (half cilinder)
  - → power pulsing at room T
- $ightharpoonup \Delta T \simeq 1^{\circ} C$  over the gas volume
  - → uniform pad plane temperature
- less material comparing to existing experiments
- The development of a micro-channel cooling plate using 3D printing technology is currently in progress
  - was conducted in 2021



Temperature History 14-15.10.2021



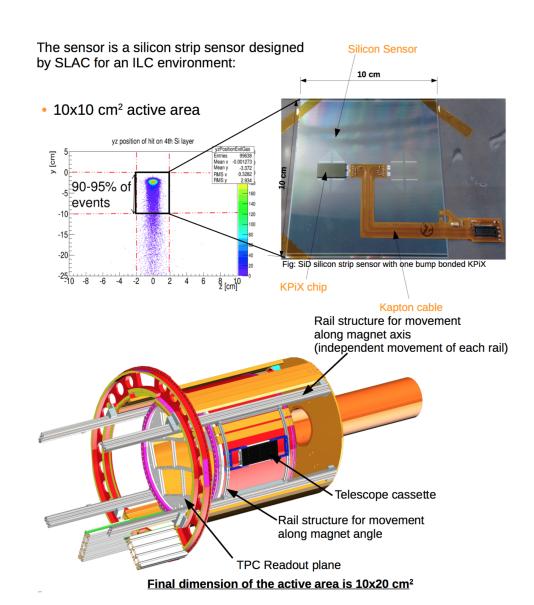


# Facility Upgrade: Large Prototype 2 (LP2)



- Further studies toward the technology choice will be carried out with upgraded LP2
  - new mechanical design of endplate:
    no space between modules
  - new large area strip telescope within solenoid with Si sensor: (project LYCORIS )
    - $\rightarrow 10 \text{x} 10 \text{ cm}^2$  active area
    - $\rightarrow$  320  $\mu m$  thickness
    - $\rightarrow 0.3\%X_0$  material budget
    - $\rightarrow$  25  $\mu m$  strip pitch to meet momentum resolution
    - → integrated pitch adapter and digital readout (KPiX)

System is under final review before send off to production and funded by EU AIDA2020



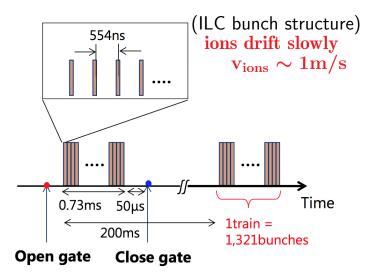


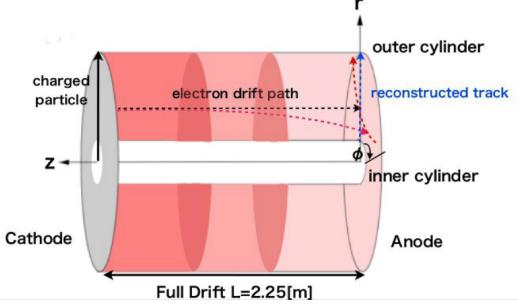


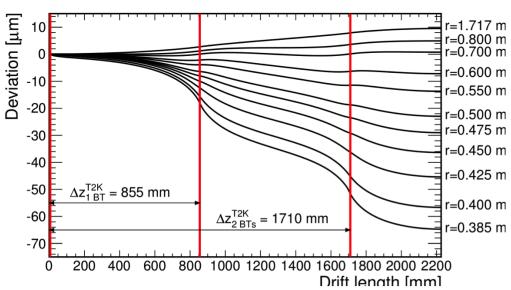


### Ion Space Charge can deteriorate the position resolution of TPC

- Primary ions yield distortions in the E-field which result to  $O(\leq 1\mu\mathrm{m})$  track distortions
- Secondary ions yield distortions from backflowing ions generated in the gas-amplification region:
  - for the case of 2 ion disks







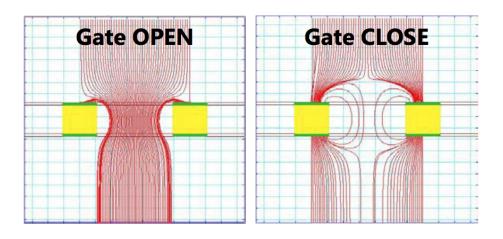
#### Gate is needed!

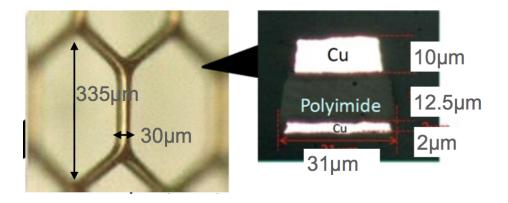


# Ion Gating

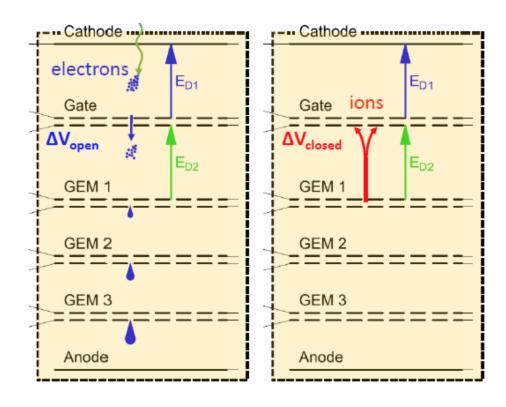


# Gating: open GEM to stop ions while keeping transparency for electrons





A large-aperture gate-GEM with honeycomb-shaped holes



The ions must be stopped before penetrating too much the drift region. The device to stop them must be transparent to electrons



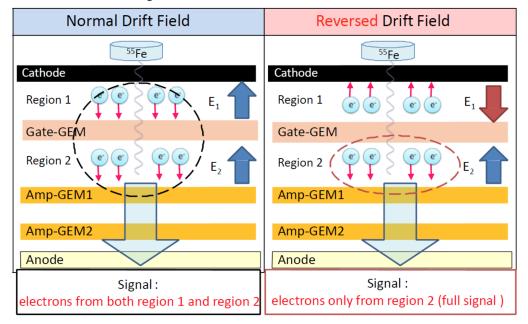
# GEM gating –Large aperture GEM transparency



# Electron transmission rate as a function of GEM voltage measured with Fe<sup>55</sup>

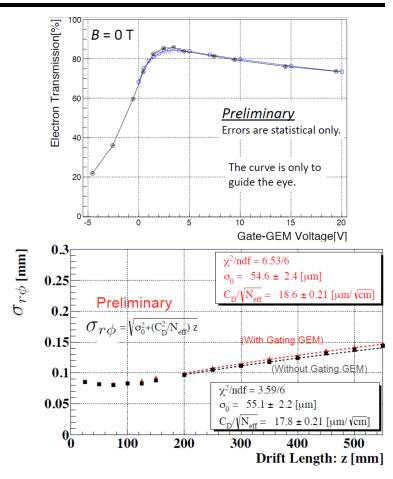
#### Measurement using 55Fe

We measured the signals with the normal and reversed drift fields for each  $\Delta V$ .



Extrapolation to 3.5 T shows acceptable transmission for electrons (80%)

Simulation shows that ion stopping power better than  $10^{-4}$  at 10 V reversed biases



- The results are consistent with no more degradation than expected ( 10%)
  - M. Kobayashi, et al., NIM A (918), 41-53